

Expertise

Expert Opinion of the Notified Body on the Conformity Assessment according to Article 10.5 of R&TTE Directive 1999/5/EC

PHOENIX TESTLAB EU Identification Number 0700

EU Identification Number 0700		
Recognised by	Bundesnetzagentur	
	BNetzA-bS-02/51-55	
Expertise No.	16-210200	
Certificate Holder	Shenzhen Huaptec Co.,Ltd.	
Address	5th FL, E BLDG, Sogood Science Park, Hangkong Road, Xixiang, Bao'an, Shenzhen, China	
Product Description	Wireless Signal Booster/ Mobile Signal Booster/RF Repeater; with LTE	
Brand Name / Model Name	Huaptec / F23H-L-800-2600-70-75, F20H-L-800- 2600-65-70, F17H-L-800-2600-65-65, F13H-L- 800-2600-60-65, F10H-L-800-2600-60-65	
Opinion on the Essential Requirements		
Article 3.1a): Health and Safety	No remarks	
Article 3.1b): Electromagnetic Compatibility	No remarks	
Article 3.2: Effective Use of the Radio Spectrum	No remarks	

CE-marking

Marking Example (Class 2)

(€ 0700 ①

This certificate is issued in accordance with the Directive 1999/5/EC of the European Parliament and the Council on radio equipment and telecommunications terminal equipment and the mutual recognition of their conformity dated 9th March 1999 and is only valid in conjunction with the following annex (2 pages).

Blomberg, 28 January 2016

Place, Date of Issue



Signed by Alan Lane Notified Body

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Technical description

Frequency Range	E-UTRA FDD Band 7: Downlink: 2620 - 2690 MHz Uplink: 2500 - 2570MHz E-UTRA FDD Band 20: Downlink: 791 - 821 MHz Uplink: 832 - 862 MHz
Transmitted Power	Downlink: Max. 23 dBm Uplink: Max. 17 dBm
Bandwidth	5, 10, 15, 20 MHz
Operational temperature range Device	-10 ~ 40 degree Celsius
Operational temperature range Power adaptor	40 degree Celsius

Technical Construction File (TCF):

Technical documentation according to Annex II sub clause 4:

 User Manual 	 Operational Description
Block Diagram	Circuit Diagram
Parts Placement	PCB-Layout
Parts List	
Hardware Version:	F25H0-2S-V04
Software Version:	V1.0

Applied Standards and Test Reports

Specification	Laboratory	Test Report Number
EN 60950-1:2006+A11:2009+ A1:2010+A12:2011+A2:2013	EMTEK (Shenzhen) CO., LTD.	ES151221044S Ver.1.0
EN 60950-1:2006+A11:2009+ A1:2010+A12:2011+A2:2013	Shenzhen LCS Compliance Testing Laboratory Ltd.	LCS1512141111S
EN 50385:2002	Shenzhen LCS Compliance Testing Laboratory Ltd.	LCS1512141124E
EN 301 489-1 V1.9.2 EN 301 489-23 V1.5.1	Shenzhen LCS Compliance Testing Laboratory Ltd.	LCS1512141123E
EN 301 908-1 V6.2.1 EN 301 908-15 V5.2.1	Shenzhen LCS Compliance Testing Laboratory Ltd.	LCS1512141122E
Further Decuments		

Further Documents

EU Declaration of Conformity, 2 pages, 2016-01-15. Product Similarity Declaration, 1 page, 2015-12-10.



Opinion on the Essential Requirements:

The basis of this Expertise is the Technical Construction File (TCF). If the TCF includes test reports issued by laboratories accredited to the standard ISO/IEC 17025, the test results of these reports are considered as a basis for the conformity assessment of the Notified Body.

Article 3.1a): Health and Safety:

Conform.

Article 3.1b): Electromagnetic Compatibility:

• Conform.

Article 3.2: Effective Use of the Radio Spectrum:

• Conform.

General Remarks:

- This conformity assessment is limited to the essential requirements of the R&TTE Directive. Only products fulfilling all essential requirements of all applicable new approach directives may be placed on the market and put into service. Products in compliance with all provisions of the applicable directives providing for the CE marking must bear this marking.
- Before putting a product on the market which uses non harmonised frequencies (Class 2) the national authorities of the member states have to be notified.
- The user shall be informed by the person placing the product onto the market if an individual confirmation by network operators may be required for using in EC member states.
- The Technical Construction File should include the following technical documentation additionally:
 - Sub board of PCB layers

